# Savitribai Phule Pune University Faculty of Science & Technology



Curriculum

# For

# Bachelor of Vocational (Engg) First Year ELECTRONIC MANUFACTURING SERVICES (Choice Based Credit System) (2019 Course)

(With Effect from Academic Year 2019-20)

#### **1.** Course Objectives

After successfully completing the vocational course, the student would have acquired relevant appropriate and adequate technical knowledge together with the professional skills and competencies in the field of Electronics Manufacturing Service so that he/she is properly equipped to take up gainful employment in this Vocation. Thus he/she should have acquired:-

#### A. Understanding of

(a) The relevant basic concepts and principles in basic science subjects (Physics, Chemistry and Mathematics) so that the students is able to understand the different vocational subjects.

(b) The basic concepts in engineering drawing.

(c) The concepts, principles of working of basic electronic devices and circuits.

(d) The knowledge of testing procedure of components and circuits by making use of different test instruments.

(e) The procedure of making P.C.B.

(f) The concepts and principles used in Radio/Audio/Video Systems and Communication devices and its maintenance.

#### B. Adequate Professional Skills and Competencies in

- (a) Testing different electronic components.
- (b) Testing the performance of electronic circuits.
- (c) Locating the fault at component level and at the stage level.

#### C. A Healthy and Professional Attitude so that the student has

- (a) An analytical approach while working on a job.
- (b) An open mind while locating/rectifying faults.
- (c) Respect for working with their own hands.
- (d) Respect for honesty, punctuality and truthfulness

**D.** NSQF compliant skills in Qualification developed by sector skill council in Electronic sector

#### 3. Course Structure:

The course will consist of combination of practice, theory and hands on skills in the electronics sector.

#### **Curriculum:**

The curriculum in each of the years of the programme would be a suitable mix of general education and skill components.

#### **Skill Development Components:**

• The focus of skill development components shall be to equip students with appropriate knowledge, practice and attitude, to become work ready. The skill development components will be relevant to the industry as per its requirements.

• The curriculum will necessarily embed within itself, National

Occupational Standards (NOSs) of specific job roles within the industry. This would enable the students to meet the learning outcomes specified in the NOSs.

- The overall design of the skill development component along with the job roles selected will be such that it leads to a comprehensive specialization in few domains.
- The curriculum will focus on work-readiness skills in each of the year of training.
- Adequate attention will be given in curriculum design to practical work, on the job training, development of student portfolios and project work.

#### **General Education Component:**

- The general education component adheres to the normal senior secondary and university standards. It will emphasize and offer courses which provide holistic development. However, it will not exceed 40% of the total curriculum.
- Adequate emphasis is given to language and communication skills.

|                |   |                         | ·                      |          |        | Electr  | onics | Manu    | facturin     | g Serv  | ices    |       |  |
|----------------|---|-------------------------|------------------------|----------|--------|---------|-------|---------|--------------|---------|---------|-------|--|
|                | B. Voc Electronics Manufacturing Services Syllabus for First Year   |                         |                        |          |        |         |       |         |              |         |         |       |  |
|                | Structure for Semester-I  |                         |                        |          |        |         |       |         |              |         |         |       |  |
| Course<br>Code | Course Name   | Teac<br>Scho<br>(Hours  | hing<br>eme<br>/Week)  | Ex       | amina  | tion So | cheme | and M   | Iarks        |         | Credits |       |  |
|                |   | Theory                  | Practical              | ISE      | ESE    | ΓW      | PR    | OR      | Fotal        | ΓH      | PR      | Fotal |  |
| 101            | Electronic Measurement and<br>Instrumentation –I  | 03                      |                        | 50       | 50     |         |       |         | 100          | 03      |         | 03    |  |
| 102            | Identification of Components,<br>Tools, SOP & Work Instructions-I   | 03                      |                        | 50       | 50     |         |       |         | 100          | 03      |         | 03    |  |
| 103            | Tools, Equipment & Safety<br>Measures –1  | 03                      |                        | 50       | 50     |         |       |         | 100          | 03      |         | 03    |  |
| 104            | Soldering & De-Soldering of<br>Components–I   | 03                      |                        | 50       | 50     |         |       |         | 100          | 03      |         | 03    |  |
| 105            | Identification of Components,<br>Tools, Equipment and its<br>working –Lab   |                         | 02                     |          |        |         | 50    |         | 50           |         | 1.5     | 1.5   |  |
| 106            | Electronic Measurement and<br>Instrumentation -I –Lab   |                         | 02                     |          |        |         | 50    |         | 50           |         | 1.5     | 1.5   |  |
| 107            | On Job Training   | <u> </u>                | 18                     | <u> </u> |        | 100     |       |         | 100          |         | 15      | 15    |  |
|                | Total   | 12                      | 22                     | 200      | 200    | 100     | 100   |         | 600          | 12      | 18      | 30    |  |
|                |   | Structure               | <mark>e for Sen</mark> | nester-J | п      |         |       |         |              |         |         |       |  |
| Course<br>Code | Course Name   | Teac<br>Sche<br>(Hours) | hing<br>eme<br>/Week)  | Ex       | camina | tion So | cheme | and M   | <b>farks</b> | Credits |         | lits  |  |
|                |   | Th                      | Prac                   | ISE      | ESE    | TW      | PR    | OR      | Total        | HT      | PR      | Total |  |
| 201            | Electronic Measurement and<br>Instrumentation –II   | 03                      |                        | 50       | 50     |         |       | <b></b> | 100          | 03      |         | 03    |  |
| 202            | Identification of Components,<br>Tools, SOP & Work Instructions-<br>II  | 03                      |                        | 50       | 50     |         |       |         | 100          | 03      |         | 03    |  |
| 203            | Tools, Equipment & Safety<br>Measures –II   | 03                      |                        | 50       | 50     |         |       |         | 100          | 03      |         | 03    |  |
| 204            | Soldering & De-soldering of<br>Components & Emergency –II   | 03                      |                        | 50       | 50     |         |       |         | 100          | 03      |         | 03    |  |
| 205            | Soldering & De-Soldering of<br>Components-Lab   |                         | 02                     |          |        |         | 50    |         | 50           |         | 1.5     | 1.5   |  |
| 206            | Electronic Measurement and<br>Instrumentation -II –Lab  |                         | 02                     |          |        |         | 50    |         | 50           |         | 1.5     | 1.5   |  |
| 207            | On Job Training   |                         | 18                     | !        |        | 100     |       |         | 100          |         | 15      | 15    |  |
|                | Total   | 12                      | 22                     | 200      | 200    | 100     | 100   |         | 600          | 12      | 18      | 30    |  |
|                | *On Job Training should be carried out in any one subject per semester as per NSDC Guide<br>lines for following Skill Sets: |                         |                        |          |        |         |       |         |              |         |         |       |  |

- 1. Embedded Software Engineer (ELE/Q1501)
- 2. Security Pack-security surveillance and access control supervisor (ELE/Q4611)
- 3. Systems Analyst (ELE/Q8701)
- Smartphone Repair Technician (ELE/Q8104)
   Business Development Executive (ELE/Q1101)

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# Syllabus

## Name of the Course: B. Vocational (Electronics Manufacturing Services)

#### Semester I

| Subject Name: Electronic Measurements and Instrumentation-I |                           |                    |  |  |
|---|---------------------------|--------------------|--|--|
| Course Code :101  | Semester: I               |                    |  |  |
| Weekly Teaching Hours: TH: 03 Tut: 00                       | Scheme of Marking TH: 100 | ISE: 50<br>ESE: 50 |  |  |
|   | Scheme of Marking PR: 50  |                    |  |  |
| Credit: 3   |                           |                    |  |  |

|            | Content   | Hours |
|------------|---|-------|
| Unit – I   | 1.0. Unit, dimensions and standards   | 12    |
|            | Scientific notations and metric prefixes. SI electrical units, SI temperature scales, Other unit systems, dimension and standards.  |       |
| Unit – II  | 2.0. Measurement Errors   | 12    |
|            | Gross error, systematic error, absolute error and relative error, accuracy,<br>precision, resolution and significant figures, Measurement error combination,<br>basics of statistical analysis. |       |
| Unit – III | 3.0. Analog meters  | 12    |
|            | PMMC instrument, galvanometer, DC ammeter, DC voltmeter, series ohm meter Transistor voltmeter circuits, AC electronic voltmeter.   |       |
| Unit – IV  | 4.0. Digital meters   | 9     |
|            | Current measurement with electronic instruments, probes Digital voltmeter systems, digital multimeters, digital frequency meter system.   |       |

| Books:   |  |                  |
|--|--|------------------|
| Name of Authors  | Title of the Book                                    | Publisher        |
| Kalsi H S  | Electronic Instrumentation                           | Mcgraw Higher Ed |
| Albert D. Helfrick, William David<br>Cooper                                  | Modern Electronic Instrumentation and<br>Measurement | PHI              |
| A Course in Electrical and<br>Electronic Measurements and<br>Instrumentation | A. K. Sawhney, Puneet Sawhney                        | Rai              |

Electronics Manufacturing Services

Subject Name: Identification of Components, Tools, SOP & Work Instructions-I

| Course Code :102                      | Semester: I               |                     |
|---------------------------------------|---------------------------|---------------------|
| Weekly Teaching Hours: TH: 03 Tut: 00 | Scheme of Marking TH: 100 | ISE: 50,<br>ESE: 50 |
|                                       | Scheme of Marking PR: 50  |                     |
| Credit:3                              |                           |                     |

|            | Content   | Hours |
|------------|---|-------|
| Unit – I   | 1.0. Main components & modules/ sub-assemblies of electronic  | 12    |
|            | Control Panel (System Controller), Keypads, Door and Window Contacts,<br>Motion Detectors, Glass Break Detection, Smoke Detectors, Heat Sensors,<br>Carbon Monoxide Detectors, Water Detectors (or Water Bug), Temperature<br>Sensors, Capacitance switches / control push buttons & rotary switches. |       |
| Unit – II  | 2.0. Digital Electronics  | 12    |
|            | Electronic controls in a common way, Counters, Flip- flops, Logic gates,<br>Multiplexers, Decoders.   |       |
| Unit – III | 3.0. Amplification factors  | 12    |
|            | Concept of Amplification factor, Gain & Signal distortion   |       |
| Unit – IV  | 4.0. TCP/IP   | 09    |
|            | Protocols like TCP/TP for communication purpose and for digital networks & circuits.  |       |

| Books:              |                                       |                   |
|---------------------|---------------------------------------|-------------------|
| Name of Authors     | Title of the Book                     | Publisher         |
| Andrew S. Tanenbaum | Computer Network                      | Pearson           |
| Jon S. Wilson       | Sensor Technology Handbook - Volume 1 | Newnes Pub.       |
| Kennedy             | Electronic Communication Systems      | Tata MC Graw Hill |

## Subject Name: Tools, Equipment and Safety Measures-I

| Course Code : 103                     | Semester: I                                 |
|---------------------------------------|---|
| Weekly Teaching Hours: TH: 03 Tut: 00 | Scheme of Marking TH: 100, ISE: 70, ESE: 30 |
|                                       | Scheme of Marking PR:                       |
| Credit:3                              |   |

|            | Content   | Hours |
|------------|---|-------|
| Unit – I   | 1.0. Types of Cables  | 12    |
|            | Classification of cables: Non-metallic Sheathed Cable, Un-grounded /<br>grounded Power supply cable, metallic Sheathed Cable, Multi-Conductor<br>Cable, Coaxial Cable, Unshielded Twisted Pair Cable, Shielded twisted pair |       |
|            | cable, Ribbon Cable, Armored & Unarmored Cable, Twin-Lead Cable, Twin<br>Axial Cable, Optical fiber cable.  |       |
| Unit – II  | 2.0. Specification and material of Cables   | 12    |
|            | Study of material and electrical Specification of all cables in Unit-I  |       |
| Unit – III | 3.0. Connectors and sockets   | 12    |
|            | Study of Connectors and sockets for all types of cables and electrical devices  |       |
| Unit – IV  | 4.0. ESD Clothing   | 09    |
|            | What to wear, how to wear   |       |

| Books:                      |  |                   |
|-----------------------------|--|-------------------|
| Name of Authors             | Title of the Book                            | Publisher         |
|                             | Cable Assemblies, Cables, Connectors and     | International     |
|                             | Passive Microwave Components: Screening      | Electro technical |
|                             | Attenuation Measurement by the Reverberation | Commission        |
|                             | Chamber Method                               |                   |
| William G. Duff             | Cables and Connector                         | IET Digital       |
|                             |  | Library           |
|                             | Hardware Book,                               |                   |
|                             | http://www.hardwarebook.info/                |                   |
| Andrew S. Tanenbaum,, David | Computer Network                             | Pearson           |
| J. Wetherall                |  |                   |
| Albert D. Helfrick, William | Modern Electronic Instrumentation            | PHI               |
| David Cooper                | and Measurement                              |                   |

# Subject Name: Soldering & De-Soldering of Components-I

| Course Code :104                      | Semester: I                               |
|---------------------------------------|---|
| Weekly Teaching Hours: TH: 03 Tut: 00 | Scheme of Marking TH: 100 ISE: 50 ESE: 50 |
|                                       | Scheme of Marking PR:                     |
| Credit:3                              |   |

|            | Content  | Hours |
|------------|--|-------|
| Unit – I   | 1.0. Soldering Tools   | 09    |
|            | Different types of Soldering Guns related to Temperature and wattages, types of tips, Solder materials and their grading.  |       |
| Unit – II  | 2.0. Soldering and De Soldering Stations   | 09    |
|            | Soldering and De Soldering Stations and their Specifications, Preparing<br>Component for Soldering.  |       |
| Unit – III | РСВ  | 09    |
|            | PCB Applications, Types of PCB, Soldering Basic Components on PCB.   |       |
| Unit – IV  | De soldering tools   | 09    |
|            | De soldering Basic Components, Safety precautions while Soldering & De soldering, Check for cold continuity of PCB.  |       |
| Unit – V   | Identification of Faults   | 09    |
|            | Identification of loose/dry solder, broken tracks on printed wire assemblies<br>& discrete components mounted circuit boards , Join the broken PCB track<br>and test, De soldering using Pump and wick, Introduction of SMD<br>Components. |       |

| Books:                |   |                  |  |
|-----------------------|---|------------------|--|
| Name of Authors       | Title of the Book                                   | Publisher        |  |
|                       | http://spoken-                                      |                  |  |
|                       | tutorial.org/watch/KiCad/Designing+printed+circuit+ |                  |  |
|                       | board+in+KiCad/Hindi/                               |                  |  |
| Bruce R. Archambeault | PCB Design for Real-World EMI Control               | Springer Science |  |
| and James Drewniak    |   |                  |  |
| Kraig Mitzner         | Complete PCB Design Using OrCad Capture and         | Newnes Pub       |  |
|                       | Layout  |                  |  |
|                       |   |                  |  |
|                       |   |                  |  |

| Electronics | Manufacturing | Services |
|-------------|---------------|----------|

#### Subject Name: Identification of Components, Tools, SOP & Work Instructions-I - Lab

| Course Code :105                 | Semester: I              |
|----------------------------------|--------------------------|
| Weekly Practical: PR: 01 Tut: 00 |                          |
|                                  | Scheme of Marking PR: 50 |
| Credit:1.5                       |                          |

Content

1. Identification & working of various electronic components (1.a., 1.b and 1.c. for any three group of components)

2. Working of testing equipment (2.a., 2.b and 2.c. for any two equipments)

3. a. Measurement using Multimeter

3. b. Measurement using Clamp meter

4. Battery health check-up

5. Measure and test the voltage of given cells.

**Electronics Manufacturing Services** 

#### Subject Name: Electronic Measurement and Instrumentation -I Lab

| Course Code : 106                 | Semester: I              |
|-----------------------------------|--------------------------|
| Weekly Practicals: PR: 01 Tut: 00 |                          |
| TH Exam Duration:                 | Scheme of Marking PR: 50 |
| Credit:1.5                        |                          |

Content

1. a. Study of semiconductor diode voltmeter

1. b. Its use as DC average responding AC voltmeter.

2. a. Study of construction of L.C.R. bridge

2. b. Determination of the value of the given components using LCR Q meter.

3. Study of distortion factor meter and determination of the % distortion of the given oscillator.

4. Study of the diode testing and determination of the parameters of the given diode.

5. Study of the transistor tester and determination of the parameters of the given transistors.

6. Study of the IC tester and determination of the parameters of the given IC.

7. Use a galvanometer as voltmeter.

8. Use a galvanometer as ammeter.

# **Syllabus**

## Name of the Course: B. Voc (Electronics Manufacturing Services)

#### Semester II

#### Subject Name: Electronic Measurement and Instrumentation –II

| Course Code : 201                     | Semester: II                                |
|---------------------------------------|---|
| Weekly Teaching Hours: TH: 03 Tut: 00 | Scheme of Marking TH: 100, ISE: 50, ESE: 50 |
|                                       | Scheme of Marking PR:                       |
| Credit:3                              |   |

| Content    |   | Hours |
|------------|---|-------|
| Unit – I   | Voltmeter and ammeter   | 09    |
|            | Study of Galvanometer, Voltmeter and ammeter and measuring methods  |       |
| Unit – II  | Wheatstone bridge, low resistance measurements  | 09    |
|            | Low resistance measuring instruments AC bridge theory, capacitance bridges,<br>Inductance bridges, and Q meter.   |       |
| Unit – III | CRO Construction  | 09    |
|            | CRT, wave form display, time base, dual trace oscilloscope  |       |
| Unit – IV  | CRO based measurements  | 09    |
|            | Measurement of voltage, frequency and phase by CRO, Oscilloscope probes,<br>Oscilloscope specifications and performance. Delay time based Oscilloscopes,<br>Sampling Oscilloscope, DSO, DSO applications. |       |
| Unit – V   | Instrument calibration  | 09    |
|            | Comparison method, digital multi-meters as standard instrument, calibration<br>Instrument Recorders: X-Y recorders, plotters.   |       |

| Books:                            |   |              |
|-----------------------------------|---|--------------|
| Name of Authors                   | Title of the Book                                 | Publisher    |
| Albert D. Helfrick, William David | Modern Electronic Instrumentation and Measurement | PHI          |
| Cooper                            |   |              |
| U.A.Bakshi, A.V.Bakshi            | Electrical Measurements And Measuring Instruments | Technical    |
|                                   |   | Publications |
| R.K. Rajput                       | Electrical Measurements and Measuring Instruments | S Chand      |

| Subject Name: Identification of Components, Tools, SOP & Work Instructions-II |   |  |
|---|---|--|
| Course Code : 202   | Semester: II                                |  |
| Weekly Teaching Hours: TH: 03 Tut: 00   | Scheme of Marking TH: 100, ISE: 50, ESE: 50 |  |
|   | Scheme of Marking PR:                       |  |
| Credit:3  |   |  |

|            | Content  | Hours |
|------------|--|-------|
| Unit – I   | Introduction to wireless communication   | 09    |
|            | Analog Communication: AM, FM etc   |       |
|            | Digital communication: ASK, PSK etc  |       |
|            | Wifi communication, Bluetooth communication etc  |       |
| Unit – II  | Signal Converters  | 09    |
|            | AC to DC converts, DC to AC converters, DC to DC converters, Signal conditioning,<br>Instrumentation Amplifier |       |
| Unit – III | Tools & their Uses   | 09    |
|            | Use of tester to monitor AC Power, Skin the electrical wires/cables using the wire                             |       |
|            | stripper and cutter, Main cable for control & electronic circuit wires, Crimping                               |       |
|            | tools and buses.   |       |
| Unit – IV  | Introduction to measuring equipment's  | 09    |
|            | Signal generator's, CRO, Function Generators, Frequency Counter, Logic analyzer,                               |       |
|            | Spectrum analyzer, LCRQ Meter.   |       |
| Unit – V   | Standard Operating Procedures and Work Instructions  | 09    |
|            | What is SOP and WI, How to read & follow SOP and WI, Overall Quality   |       |
|            | Assurance Plan.  |       |

| Books                             |                                       |              |
|-----------------------------------|---------------------------------------|--------------|
| Name of Authors                   | Title of the Book                     | Publisher    |
| Behrouz A. Forouzan, Sophia Chung | Data Communications and Networking    | McGraw Hill  |
| Fegan                             |                                       |              |
| Andrew S. Tanenbaum,, David J.    | Computer Network                      | Pearson      |
| Wetherall                         |                                       |              |
| Albert D. Helfrick, William David | Modern Electronic Instrumentation and | PHI          |
| Cooper                            | Measurement                           |              |
| P. S. Bimbhra                     | Power Electronics                     | Khanna       |
|                                   | Electrical Measurements And           |              |
| U.A.Bakshi, A.V.Bakshi            | Measuring                             | Technical    |
|                                   | Instruments                           | Publications |

# Subject Name: Tools, Equipment & Safety Measures –II

| Course Code : 203                     |  | Semester: II                    |             |
|---------------------------------------|--|---------------------------------|-------------|
| Weekly Teaching Hours: TH: 03 Tut: 00 |  | Scheme of Marking TH: 100, ISE: | 50, ESE: 50 |
|                                       |  | Scheme of Marking PR:           |             |
| Credit:3                              |  |                                 |             |
|                                       | Conte  | ent                             | Hours       |
| Unit – I                              | Tools & Equipment  |                                 | 09          |
|                                       | Study of all types of tools used in manufacturing.             |                                 |             |
| Unit – II                             | Equipments   |                                 | 09          |
|                                       | Study of all equipment required and deployed in manufacturing. |                                 |             |
| ·                                     |  |                                 | 0.0         |

| Unit – III | Installing & servicing processes   | 09 |
|------------|--|----|
|            | Installing & servicing, Identification and termination process, General maintenance of tools/equipment and recalibration of Test equipment, General safety and common- |    |
|            | Sense safety.  |    |
| Unit – IV  | PPE  | 09 |
|            | Usage & benefits of PPE, Electronics Manufacturing Services and Types & usage of Various PPE, Maintenance of PPE.  |    |
| Unit – V   | Clean Room Environment   | 09 |
|            | Do's and Don't and Shop Floor Discipline.  |    |

| Books                         |  |                   |
|-------------------------------|--|-------------------|
| Name of Authors               | Title of the Book                        | Publisher         |
| R. S. Khandpur                | Troubleshooting Electronic Equipment     | McGraw Hill       |
|                               |  | Professional      |
| David Herres                  | Troubleshooting and Repairing Commercial | McGraw Hill       |
|                               | Electrical Equipment                     | Education         |
| John Cadick, Mary Capelli-    | Electrical Safety Handbook 3E            | Delmar Publishers |
| Schellpfeffer, Dennis Neitzel |  |                   |
| W Fordham Cooper              | Electrical Safety Engineering            | Newnes-           |
|                               |  | Butterworths      |

| Su         | bject Name: Soldering & De-Soldering   | of Components & Emergency actions   | II    |  |  |
|------------|--|---|-------|--|--|
| Course Coo | le : 204 Sei   | nester: II  |       |  |  |
| Weekly Tea | Weekly Teaching Hours: TH: 03 Tut: 00Scheme of Marking TH: 100, ISE: 50, ESE:  |   |       |  |  |
|            | Scl  | neme of Marking PR:   |       |  |  |
| Credit:3   |  |   |       |  |  |
|            | Content  |   | Hours |  |  |
| Unit – I   | Introduction to SMD Components   |   | 09    |  |  |
|            | Identification of 2, 3 and 4 terminal SMD  | components.   |       |  |  |
| Unit – II  | Soldering the SMD components   |   | 09    |  |  |
|            | Soldering the SMD components on the PC<br>soldering station to solder various ICs of c<br>clamping tools, Identify various connectio<br>Soldering station. | B, Make the necessary settings on SMD<br>lifferent packages by choosing proper<br>ns and the setup required for SMD |       |  |  |
| Unit – III | De soldering   |   | 09    |  |  |
|            | De solder the SMD components from the<br>on SMD soldering station to de solder var<br>Choosing proper clamping tools.                                      | given PCB, Make the necessary settings ious ICs of different packages by  |       |  |  |
| Unit – IV  | Make a panel board   |   | 09    |  |  |
|            | Make a panel board using different types<br>Identification of crimping tools for variou<br>Practices.  | of switches for a given application,<br>s IC packages and Reliable Soldering  |       |  |  |
| Unit – V   | Emergency actions  |   | 09    |  |  |
|            | Minimum Requirements, Reporting Emer<br>secondary evacuation routes, Locations of<br>Stations' location, Assembly points and M                             | gencies, Emergency exits, Primary and<br>fire extinguishers, Fire alarm pull<br>fedical Services.                   |       |  |  |

| Books                         |   |               |
|-------------------------------|---|---------------|
| Name of Authors               | Title of the Book                           | Publisher     |
| R. Sengupta                   | Principles of Reliable Soldering Techniques | New Age       |
|                               |   | International |
| Ray P. Prasad                 | Surface Mount Technology: Principles and    | Springer      |
|                               | Practice                                    |               |
| Mel M. Schwartz               | Soldering: Understanding the Basics         | ASM           |
|                               |   | International |
| John Cadick, Mary Capelli-    | Electrical Safety Handbook 3E               | Delmar        |
| Schellpfeffer, Dennis Neitzel |   |               |
| W Fordham Cooper              | Electrical Safety Engineering               | Newnes-       |
|                               |   | Butterworths  |

#### Subject Name: Soldering & De-Soldering of Components-Lab

| Course Code : 205                 | Semester: II             |
|-----------------------------------|--------------------------|
| Weekly Practicals: PR: 01 Tut: 00 | Scheme of Marking TH:    |
| TH Exam Duration:                 | Scheme of Marking PR: 50 |
| Credit:1.5                        |                          |

#### Content

1. Study of soldering and de soldering tools and machinery (any 2 tools)

2. Assemble the product (any 3 products)

3. Dis-assemble the product (any 3 products)

4. Safety Precautions & emergency plans (study of minimum 2 methods)

| Subject manne. Electronic measurement and in | instrumentation -11 Lab |
|--|-------------------------|
| Code : 206 Semester: II                      |                         |

| Course Code : 206                 | Semester: II             |
|-----------------------------------|--------------------------|
| Weekly Practicals: PR: 01 Tut: 00 | Scheme of Marking TH:    |
| TH Exam Duration:                 | Scheme of Marking PR: 50 |
| Credit:1.5                        |                          |

| Content |
|---------|

1. Study of the following transducer

(i) PT-100 trans (ii) J- type

trans. (iii) K-type trans (iv)

Presser trans

2. a. Measurement of phase difference

2. b. Measurement of frequency using CRO (lissajous figure)

3. Measurement of low resistance Kelvin's double bridge.

4. Radio Receiver Measurements (any 3 parameter measurements

# Savitribai Phule Pune University

Faculty of Science & Technology



Curriculum

For

# **Bachelor of Vocational (Engg)**

First Year ELECTRONIC MANUFACTURING SERVICES

(Choice Based Credit System) (2019 Course)

(With Effect from Academic Year 2019-20)

#### 1. Course Objectives

After successfully completing the vocational course, the student would have acquired relevant appropriate and adequate technical knowledge together with the professional skills and competencies in the field of Electronics Manufacturing Service so that he/she is properly equipped to take up gainful employment in this Vocation. Thus he/she should have acquired:-

#### A. Understanding of

(a) The relevant basic concepts and principles in basic science subjects

(Physics, Chemistry and Mathematics) so that the students is able to understand the different vocational subjects.

(b) The basic concepts in engineering drawing.

(c) The concepts, principles of working of basic electronic devices and circuits.

(d) The knowledge of testing procedure of components and circuits by making use of different test instruments.

(e) The procedure of making P.C.B.

(f) The concepts and principles used in Radio/Audio/Video Systems and Communication devices and its maintenance.

#### B. Adequate Professional Skills and Competencies in

(a) Testing different electronic components.

- (b) Testing the performance of electronic circuits.
- (c) Locating the fault at component level and at the stage level.

#### C. A Healthy and Professional Attitude so that the student has

- (a) An analytical approach while working on a job.
- (b) An open mind while locating/rectifying faults.
- (c) Respect for working with their own hands.
- (d) Respect for honesty, punctuality and truthfulness

**D.** NSQF compliant skills in Qualification developed by sector skill council in Electronic sector

#### **3. Course Structure:**

The course will consist of combination of practice, theory and hands on skills in the electronics sector.

#### **Curriculum:**

The curriculum in each of the years of the programme would be a suitable mix of general education and skill components.

#### **Skill Development Components:**

• The focus of skill development components shall be to equip students with appropriate knowledge, practice and attitude, to become work

ready. The skill development components will be relevant to the industry as per its requirements.

• The curriculum will necessarily embed within itself, National Occupational Standards (NOSs) of specific job roles within the industry. This would enable the students to meet the learning outcomes specified in the NOSs.

• The overall design of the skill development component along with the job roles selected will be such that it leads to a comprehensive specialization in few domains.

• The curriculum will focus on work-readiness skills in each of the year of training.

• Adequate attention will be given in curriculum design to practical work, on the job training, development of student portfolios and project work.

#### **General Education Component:**

- The general education component adheres to the normal senior secondary and university standards. It will emphasize and offer courses which provide holistic development. However, it will not exceed 40% of the total curriculum.
- Adequate emphasis is given to language and communication skills.

|                | S  | tructure              | for Sen                  | nester-I                             |       |          |      |       |       |    |      |       |
|----------------|--|-----------------------|--------------------------|--------------------------------------|-------|----------|------|-------|-------|----|------|-------|
| Course<br>Code | Course Name                                    | Tea<br>Sch<br>(Hours  | ching<br>teme<br>s/Week) | Examination Scheme and Marks Credits |       |          |      |       | its   |    |      |       |
|                |  | Th                    | Prac                     | ISE                                  | ESE   | TW       | PR   | OR    | Total | ТН | PR   | Total |
|                | Fault analysis & Repair                        | 03                    |                          | 50                                   | 50    |          |      |       | 100   | 03 |      | 03    |
|                | Good Manufacturing Concept & Practices – I     | 03                    |                          | 50                                   | 50    |          |      |       | 100   | 03 |      | 03    |
|                | Electronics Devices and Circuit –I             | 03                    |                          | 50                                   | 50    |          |      |       | 100   | 03 |      | 03    |
|                | Electronics System Packaging and Manufacturing | 03                    |                          | 50                                   | 50    |          |      |       | 100   | 03 |      | 03    |
|                | Electronics Devices and Circuit-I Lab          |                       | 02                       |                                      |       |          | 50   |       | 50    |    | 1.5  | 1.5   |
|                | Fault analysis & Repairs - Lab                 |                       | 02                       |                                      |       |          | 50   |       | 50    |    | 1.5  | 1.5   |
|                | On Job Training                                |                       | 18                       |                                      |       | 100      |      |       | 100   |    | 15   | 15    |
|                | Total  | 12                    | 22                       | 200                                  | 200   | 100      | 100  |       | 600   | 12 | 18   | 30    |
|                | Si   | ructure               | for Sem                  | ester-II                             |       |          |      |       |       |    |      |       |
| Course<br>Code | Course Name                                    | Teac<br>Sch<br>(Hours | ching<br>eme<br>/Wee k)  | Ex                                   | amina | tion Scl | heme | and M | larks |    | Cred | its   |
|                |  | Th                    | Prac                     | ISE                                  | ESE   | TW       | PR   | OR    | Total | ТН | PR   | Total |
|                | Good Manufacturing Concepts<br>Practices–II    | 03                    |                          | 50                                   | 50    |          |      |       | 100   | 03 |      | 03    |
|                | Manufacturing & Quality Norms                  | 03                    |                          | 50                                   | 50    |          |      |       | 100   | 03 |      | 03    |
|                | Good Manufacturing Concepts &<br>Practices–III | 03                    |                          | 50                                   | 50    |          |      |       | 100   | 03 |      | 03    |
|                | Electronics Devices Circuit –II                | 03                    |                          | 50                                   | 50    |          |      |       | 100   | 03 |      | 03    |
|                | Electronics Devices Circuit –II Lab            |                       | 02                       |                                      |       |          | 50   |       | 50    |    | 1.5  | 1.5   |
|                | Manufacturing Practices                        |                       | 02                       |                                      |       |          | 50   |       | 50    |    | 1.5  | 1.5   |
|                | On Job Training                                |                       | 18                       |                                      |       | 100      |      |       | 100   |    | 15   | 15    |
|                | Total  | 12                    | 22                       | 200                                  | 200   | 100      | 100  |       | 600   | 12 | 18   | 30    |

## B. Voc Electronics Manufacturing Services Syllabus for Second Year-

\*On Job Training should be carried out in any one subject per semester as per NSDC Guide lines for following Skill Sets:

- 1. Field Engineer RACW (ELE/Q3105)
- 2. Security System Service Engineer (ELE/Q4610)
- 3. Pre-Sales Solar Technical Support Engineer (ELE/Q5602)
- 4. Purchase Executive (ELE/Q5701)
- 5. Quality Engineer (ELE/Q7901)

# Syllabus

# Name of the Course: B. Voc (Electronics Manufacturing Services)

#### **Semester III**

#### Subject Name: Fault Analysis and Repairs

| Course Code :301                         | Semester: III              |                     |
|--|----------------------------|---------------------|
| Weekly Teaching Hours: TH: 03<br>Tut: 00 | Scheme of Marking TH: 100, | ISE: 50,<br>ESE: 50 |
|  | Scheme of Marking PR:      |                     |
| Credit:3                                 |                            |                     |

| Content    |  |    |  |  |
|------------|--|----|--|--|
| Unit – I   | Fault Classification, Identification & Rectification   | 12 |  |  |
|            | Classification of fault , Identification of fault , Rectification of fault,<br>Repairing/Replacing Module  |    |  |  |
| Unit – II  | Analysis for the different types of equipment's  | 12 |  |  |
|            | Smartphone         Air Conditioning         Security systems         Electronically controlled doors   |    |  |  |
| Unit – III | Hardware and Software Fault analysis<br>Hardware and Software Fault analysis based on hardware and software<br>component, Diagnostic and Testing Methods |    |  |  |
| Unit – IV  | Visual Inspection  | 09 |  |  |

Earth Continuity Test

Insulation Resistance Test

| Books           |                                      |                              |  |  |  |  |  |
|-----------------|--------------------------------------|------------------------------|--|--|--|--|--|
| Name of Authors | Title of the Book                    | Publisher                    |  |  |  |  |  |
| R. S. Khandpur  | Troubleshooting Electronic Equipment | McGraw-Hill<br>Education     |  |  |  |  |  |
| Philip Kiameh   | Electronic Equipment Handbook        | McGraw-<br>Hill<br>Education |  |  |  |  |  |
|                 |                                      |                              |  |  |  |  |  |

# Subject Name: Good Manufacturing Concept & Practices – I Course Code :302 Semester: III Weekly Teaching Hours: Scheme of Marking TH: 100, ISE: 50, ESE: 50 TH: 03 Tut: 00 Scheme of Marking PR: - Credit:3 Scheme of Marking PR: -

|            | Hours  |    |
|------------|--|----|
| Unit – I   | Quality Management                                 | 12 |
|            | TQM (Total Quality Management) & Kaizen            |    |
|            | Inventory Management & Logistics in brief          |    |
| Unit – II  | Quality Assurance                                  | 12 |
|            | Implementation of Quality assurance                |    |
|            | Checklist for Quality Assurance                    |    |
| Unit – III | Quality Analysis                                   | 12 |
|            | SWOT analysis                                      |    |
|            | Lean Manufacturing                                 |    |
| Unit – IV  | The 3M Model                                       | 09 |
|            | Muda, Mura & Muri – Toyota Production System (TPS) |    |
|            | Spatial considerations & other related concepts    |    |
|            |  |    |

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| Books              |                           |   |
|--------------------|---------------------------|---|
| Name of Authors    | Title of the Book         | Publisher                                       |
| David Meier, Liker | The Toyota Way Field book | McGraw-Hill<br>Education (India)<br>Pvt Limited |
| P. N.<br>MUKHERJEE | Total Quality Management  | PHI Learning                                    |
|                    |                           |   |

# Subject Name: Electronics Devices Circuit-I Course Code : 303 Semester: III Weekly Teaching Hours: TH: 03 Tut: Scheme of Marking TH: 100, ISE: 50, ESE: 50 Scheme of Marking PR: - Scheme of Marking PR: - Credit:3 Image: Scheme of Marking Preserve

|           | Content   | Hours |
|-----------|---|-------|
| Unit – I  | Energy Bands and Charge Carrier in Semiconductor:                             | 25    |
|           | Bonding forces and energy bands in solids, Charge Carriers in                 |       |
|           | Semiconductors, Carrier Concentrations, Drift Mechanism. Excess carriers in   |       |
|           | Semiconductors: Optical Absorption, Carrier Lifetime: Direct Recombination,   |       |
|           | Steady State Carrier Generation, Quasi-Fermi Level, Diffusion of carriers and |       |
|           | Einstein relation.  |       |
| Unit – II | Junctions:  | 20    |
|           | Equilibrium Conditions, Forward and Reveres Biased Junctions;                 |       |
|           | Steady State Conditions. Optoelectronic Devices: Photodiode V-I               |       |
|           | characteristic, Photo detector, Solar Cells, Light Emitting Diode             |       |

| Books                             |   |   |
|-----------------------------------|---|---|
| Name of Authors                   | Title of the Book   | Publisher   |
| Donald Neaman<br>Ramakant Gaikwad | Electronic Circuits - Analysis and Design<br>Op Amps & Linear Integrated Circuits | Mc Graw Hill, 3rd<br>Edition.<br>Pearson Education. |
| Millman Halkias                   |   | P a g e 10   24                                     |

| Phillip E. Allen and Douglas R.     | Integrated Electronics            | Oxford, 2nd      |
|-------------------------------------|-----------------------------------|------------------|
| Holberg                             | CMOS Analog Circuit               | Edition          |
| Salivahan and<br>Kanchana Bhaskaran | Design Linear Integrated Circuits | Tata McGraw Hill |

1. NPTEL Course "Analog Electronic Circuits" https://nptel.ac.in/courses/108/105/108105158/

2. NPTEL Course on "Analog Circuits" https://nptel.ac.in/courses/108/101/108101094/

### Subject Name: Electronics System Packaging and Manufacturing

| Course Code :304                         | Semester: III                             |
|--|---|
| Weekly Teaching Hours: TH: 03 Tut:<br>00 | Scheme of Marking TH: 100 ISE: 50 ESE: 50 |
|  | Scheme of Marking PR:                     |
| Credit:3                                 |   |

|            | Content   | Hours |
|------------|---|-------|
| Unit – I   | Evolution and Classification of Printed Circuit Boards  | 12    |
|            | Challenges in Modern PCB Design and Manufacture, PCB fabrication  |       |
|            | methodologies (SSB, DSB and multilayer board), PCB design considerations/   |       |
|            | design rules for analog, digital and power applications   |       |
| Unit – II  | Electromagnetic interference in electronic systems and its impact   | 12    |
|            | Analysis of electronic circuit from noise emission point of view (both conducted  |       |
|            | and radiated emission) cross talk and reflection behavior of the circuit in time  |       |
|            | domain, Thermal management of electronic devices and systems.   |       |
| Unit – III | Semiconductor Packages:   | 12    |
|            | Single chip packages or modules. (SCM) Commonly used packages and advanced packages; Materials in packages, Current trends in Packaging, Multichip modules (MCM)-types; System-in package (SIP); Packaging roadmaps |       |
| Unit – IV  | Hybrid circuits   | 09    |
|            | Pipe and FIFOs, Shared memory, Sockets  |       |
|            |   |       |

| Books           |                   |                 |
|-----------------|-------------------|-----------------|
| Name of Authors | Title of the Book | Publisher       |
|                 |                   | P a g e 12   24 |

|                       | EI  | ectronics Manufacturing Service |
|-----------------------|---|---------------------------------|
| Glenn R.<br>Blackwell | The Electronic Packaging Handbook   | CRC Press                       |
| Yong Liu              | Power Electronic Packaging<br>Design, Assembly Process, Reliability and<br>Modeling | Springer New York               |

# Subject Name: Electronic Devices and Circuits Lab Course Code :305 Semester: III Weekly Practicals: PR: 01 Tut: 00 Scheme of Marking PR: 50 Credit:1.5 Credit:1.5

#### Content

- 1. Study of Lab Equipments and Components: CRO, Multimeter, and Function Generator, Power supply- Active, Passive Components and Bread Board.
- 2. P-N Junction diode: Characteristics of PN Junction diode Static and dynamic resistance measurement from graph.
- 3. Applications of PN Junction diode: Half & Full wave rectifier- Measurement of Vrms, Vdc, and ripple factor.
- 4. Characteristics of Zener diode: V-I characteristics of zener diode, Graphical measurement of forward and reverse resistance.
- 5. Application of Zener diode: Zener diode as voltage regulator. Measurement of percentage regulation by varying load resistor.

#### Subject Name: Fault Analysis & Repairs Lab

| Course Code : 306                 | Semester: III            |
|-----------------------------------|--------------------------|
| Weekly Practicals: PR: 01 Tut: 00 | Scheme of Marking TH:    |
| TH Exam Duration:                 | Scheme of Marking PR: 50 |
| Credit:1.5                        |                          |

#### Content

- 1. Categorization of faults
  - a. Hardware/Software, User Induced, Component Failures
  - b. L0 to L4 repairs
- 2. Testing electrical/electronic components in the product
- Troubleshoot and repair of the faults identified in the product
   Preventive Maintenance Services

## Syllabus

Name of the Course: B. Voc (Electronics Manufacturing Services)

#### Semester IV

| Subject Name: Good Manufacturing Concepts & Practices – II |   |
|--|---|
| Course Code : 401  | Semester: IV                                |
| Weekly Teaching Hours: TH: 03<br>Tut: 00                   | Scheme of Marking TH: 100, ISE: 50, ESE: 50 |
|  | Scheme of Marking PR:                       |
| Credit:3   |   |

| Content   |   | Hours |
|-----------|---|-------|
| Unit – I  | Work Study Concepts   | 25    |
|           | Method study, Work measurement, Sequencing of Operations and timing<br>the flow steps, Advantages of work study |       |
| Unit – II | Team Working  | 20    |
|           | Forming, Storming, Norming, Performing, Adjourning  |       |

| looks                           |  |                        |
|---------------------------------|--|------------------------|
| Name of Authors                 | Title of the Book  | Publisher              |
| Arvind K. Birdie,<br>Madhu Jain | Organizational Behavior and Virtual Work<br>Concepts and Analytical Approaches | Apple Academi<br>Press |
| Brian A. Griffith               | Working in Teams<br>Moving From High Potential to High<br>Performance          | SAGE<br>Publications   |

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### Subject Name: Manufacturing & Quality Norms

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| Course Code : 402                        | Semester: IV                                |
|--|---|
| Weekly Teaching Hours: TH: 03 Tut:<br>00 | Scheme of Marking TH: 100, ISE: 50, ESE: 50 |
|  | Scheme of Marking PR:                       |
| Credit:3                                 |   |

|            | Content   | Hours |
|------------|---|-------|
| Unit – I   | Manufacturing & Quality Norms   | 12    |
|            | Manufacturing & Quality Norms- keep it differently according to all<br>applications, Manpower Deployment and Operations as per Work Instructions<br>and criticality of the process Understanding how to form each operation and<br>practical training of operation, Understanding accept and reject criterion of a<br>particular operation.   |       |
| Unit – II  | Manufacturing & Quality Norms – II  | 12    |
|            | Process in packing line-Packing line Operations sequence flow and its<br>importance, Quality Systems - Accept, Reject criterion of various tests at OQA,<br>Training of Assembly of electronic components - Assemble, Check, test<br>electronic components, Various Labels and their Importance - Understanding<br>Labels, Scanning and its importance, Packing of components/devices - Various<br>Stages of packing, acceptance. |       |
| Unit – III | Training of Testing   | 12    |
|            | Practical training of testing/checking each operation, Quality Norms of accept<br>and practical training of electronic equipment's/Devices Acceptance/Rejection<br>training of various defects  |       |
| Unit – IV  | Rejection Norms   | 09    |
|            | Reject and sampling following QA norms - AQL level, Sampling techniques, as per QA sampling accept, reject numbers  |       |
|            |   |       |

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| Books                              |   |                      |  |  |
|------------------------------------|---|----------------------|--|--|
| Name of Authors                    | Title of the Book   | Publishe<br>r        |  |  |
| Charles A. Cianfrani, John E. West | ISO 9001:2015 Explained   | ASQ Quality<br>Press |  |  |
| Denise E. Robitaille               | ISO 9001:2015 Handbook for Small and<br>Medium-sized Businesses | ASQ Quality<br>Press |  |  |

| Course Co                           | ode: 403                   | Semester: IV   |       |  |  |  |
|-------------------------------------|----------------------------|--|-------|--|--|--|
| Weekly Tea<br>Tut: 00               | aching Hours: TH: 03       | Scheme of Marking TH: 100, ISE: 50, ESE: 50<br>Scheme of Marking PR: |       |  |  |  |
|                                     |                            |  |       |  |  |  |
| Credit:3                            |                            |  |       |  |  |  |
|                                     | Со                         | ntent  | Hours |  |  |  |
| Unit – I                            | Good Manufacturing Concep  | ots & Practices - II   | 12    |  |  |  |
|                                     | Brief Introduction         |  |       |  |  |  |
|                                     |                            |  |       |  |  |  |
| Unit – II Total Quality Management  |                            |  | 12    |  |  |  |
|                                     | ISO Standards & Kaizen     |  |       |  |  |  |
|                                     |                            |  |       |  |  |  |
| Unit – III Toyota Production System |                            |  | 12    |  |  |  |
|                                     | Lean Manufacturing         |  |       |  |  |  |
|                                     | Combination of Inventory   |  |       |  |  |  |
|                                     | Supply Chain               |  |       |  |  |  |
|                                     |                            |  |       |  |  |  |
| Unit – IV                           | Quality and Inspection     |  | 12    |  |  |  |
|                                     |                            |  |       |  |  |  |
|                                     | Sigma and 6 Sigma Orientat | ion  |       |  |  |  |

| Books              |                           |           |
|--------------------|---------------------------|-----------|
| Name of Authors    | Title of the Book         | Publisher |
| David Meier, Liker | The Toyota Way Field book |           |

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|                     | Electror   | nics Manufacturing Serv                         | vice |
|---------------------|--|---|------|
|                     |  | McGraw-Hill<br>Education (India)<br>Pvt Limited |      |
| P. N.<br>MUKHERJEE  | Total Quality Management                             | PHI Learning                                    |      |
| Heras-Saizarbitoria | ISO 9001, ISO 14001, and New Management<br>Standards | Springer<br>International<br>Publishing         |      |

| Course C  | ode: 404   | Semester: II   |       |  |  |  |  |
|---|--|--|-------|--|--|--|--|
| Weekly Te<br>Tut: 00  | eaching Hours: TH: 03  | Scheme of Marking TH: 100, ISE: 50, ESE: 50  |       |  |  |  |  |
|   |  | Scheme of Marking PR:  |       |  |  |  |  |
| Credit:3  |  |  |       |  |  |  |  |
|   | Content  | t  | Hours |  |  |  |  |
| Unit – I  | MOSFET:  |  | 15    |  |  |  |  |
| Device structure and its operation in equilibrium, V-I characteristics. Circuits at DC, MOSFET as Amplifier and switch, Biasing in MOS amplifier circuits, small-signal operation and models, single stage MOS amplifier, MOSFET internal capacitances and high frequency model, frequency response of CS amplifier |  |  |       |  |  |  |  |
| Unit – II BJT:  |  |  | 15    |  |  |  |  |
|   | Review of device structure operat<br>BJT as amplifier and switch, biasi<br>operation and models, single stage<br>high frequency model, frequency                                 | ion and V-I characteristics, BJT circuits at DC,<br>ng in BJT amplifier circuit, small-signal<br>e BJT amplifier, BJT internal capacitances and<br>response of CE amplifier.         |       |  |  |  |  |
| Unit –<br>III   | Jnit –<br>II FEEDBACK:   |  |       |  |  |  |  |
|   | The general feedback structure, pr<br>feedback topologies, the series-sh<br>feedback amplifier, the shunt-shu<br>Oscillators: Basic principles of sir<br>circuits, LC oscillator | roperties of negative feedback, the four basic<br>unt feedback amplifier, the series-series<br>at and shunt series feedback amplifier.<br>husoidal oscillators, op-amp RC oscillator |       |  |  |  |  |

| Books           |                   |              |
|-----------------|-------------------|--------------|
| Name of Authors | Title of the Book | Publisher    |
|                 |                   | Page 21   24 |

|                                     | Integrated Electronics-Analog and Digital | Tata                |  |  |
|-------------------------------------|---|---------------------|--|--|
| Millman Halkias                     | Circuits and Systems                      | McGraw Hill         |  |  |
| David A.Bell                        | Electronic Devices and Circuits           | Oxford press        |  |  |
| R. L. Boylstad, L. Nashlesky,       | Electronic Devices and circuits Theory    | PrenticeHall of     |  |  |
|                                     |   | India               |  |  |
| Anil K. Maini and Varsha Agarwal    | Electronic Devices and Circuits           | Wiley India         |  |  |
| Phillip E. Allen Douglas R. Holberg | CMOS Analog Circuit Design                | Oxford.             |  |  |
| 5. K. R. Botkar                     | Integrated Circuits                       | Khanna Publication  |  |  |
| Donald Neaman                       | Electronic Circuit Analysis and Design    | Tata<br>McGraw Hill |  |  |

#### Subject Name: Electronic Devices and Circuits –II Lab

| Course Code : 405                 | Semester: IV             |  |
|-----------------------------------|--------------------------|--|
| Weekly Practicals: PR: 01 Tut: 00 | Scheme of Marking TH:    |  |
| TH Exam Duration:                 | Scheme of Marking PR: 50 |  |
| Credit:1.5                        |                          |  |

#### Content

- 1. Characteristic of BJT: BJT in CE configuration- Graphical measurement of h parameters from input and output characteristics. Measurement of Av, AI, R<sub>o</sub> and R<sub>i</sub> of CE amplifier with potential divider biasing.
- 2. Measurement of Operational Amplifier Parameters: Common Mode Gain, Differential Mode Gain, CMRR, Slew Rate.
- 3. Applications of Op-amp: Op-amp as summing amplifier, Difference amplifier, Integrator and differentiator.
- 4. Field Effect Transistors: Single stage Common source FET amplifier –plot of gain in dB Vs frequency, Measurement of, bandwidth, input impedance, maximum signal handling capacity (MSHC) of an amplifier.
- 5. Oscillators: Sinusoidal Oscillators. Wien's bridge oscillator b. phase shift oscillator.

| Subject Name: Vocational Practical |                          |  |  |  |  |
|------------------------------------|--------------------------|--|--|--|--|
| Course Code : 406                  | Semester: II             |  |  |  |  |
| Weekly Practicals: PR: 01 Tut: 00  | Scheme of Marking TH:    |  |  |  |  |
| TH Exam Duration:                  | Scheme of Marking PR: 50 |  |  |  |  |
| Credit:1.5                         |                          |  |  |  |  |

#### Content

- Work study concepts
   Team work concept

# Savitribai Phule Pune University

Faculty of Science & Technology



Curriculum

For

# **Bachelor of Vocational (Engg)**

First Year ELECTRONIC MANUFACTURING SERVICES

(Choice Based Credit System) (2019 Course)

(With Effect from Academic Year 2019-20)

#### 1. Course Objectives

After successfully completing the vocational course, the student would have acquired relevant appropriate and adequate technical knowledge together with the professional skills and competencies in the field of Electronics Manufacturing Service so that he/she is properly equipped to take up gainful employment in this Vocation. Thus he/she should have acquired:-

#### A. Understanding of

(a) The relevant basic concepts and principles in basic science subjects

(Physics, Chemistry and Mathematics) so that the students is able to understand the different vocational subjects.

(b) The basic concepts in engineering drawing.

(c) The concepts, principles of working of basic electronic devices and circuits.

(d) The knowledge of testing procedure of components and circuits by making use of different test instruments.

(e) The procedure of making P.C.B.

(f) The concepts and principles used in Radio/Audio/Video Systems and Communication devices and its maintenance.

#### B. Adequate Professional Skills and Competencies in

(a) Testing different electronic components.

- (b) Testing the performance of electronic circuits.
- (c) Locating the fault at component level and at the stage level.

#### C. A Healthy and Professional Attitude so that the student has

- (a) An analytical approach while working on a job.
- (b) An open mind while locating/rectifying faults.
- (c) Respect for working with their own hands.
- (d) Respect for honesty, punctuality and truthfulness

**D.** NSQF compliant skills in Qualification developed by sector skill council in Electronic sector

#### 3. Course Structure:

The course will consist of combination of practice, theory and hands on skills in the electronics sector.

#### **Curriculum:**

The curriculum in each of the years of the programme would be a suitable mix of general education and skill components.

#### **Skill Development Components:**

• The focus of skill development components shall be to equip students with appropriate knowledge, practice and attitude, to become work

ready. The skill development components will be relevant to the industry as per its requirements.

• The curriculum will necessarily embed within itself, National Occupational Standards (NOSs) of specific job roles within the industry. This would enable the students to meet the learning outcomes specified in the NOSs.

• The overall design of the skill development component along with the job roles selected will be such that it leads to a comprehensive specialization in few domains.

• The curriculum will focus on work-readiness skills in each of the year of training.

• Adequate attention will be given in curriculum design to practical work, on the job training, development of student portfolios and project work.

#### **General Education Component:**

- The general education component adheres to the normal senior secondary and university standards. It will emphasize and offer courses which provide holistic development. However, it will not exceed 40% of the total curriculum.
- Adequate emphasis is given to language and communication skills.

|                | Str   | ucture                | for Sen                         | nester-I                     |     |     |     |         |         |    |     |       |
|----------------|---|-----------------------|---------------------------------|------------------------------|-----|-----|-----|---------|---------|----|-----|-------|
| Course<br>Code | Course Name   | Teac<br>Sch<br>(Hours | ching<br>eme<br>s/Week)         | Examination Scheme and Marks |     |     |     | Credits |         |    |     |       |
|                |   | Th                    | Prac                            | ISE                          | ESE | TW  | PR  | OR      | Total   | тн | PR  | Total |
|                | Valuation & Storage   | 03                    |                                 | 50                           | 50  |     |     |         | 100     | 03 |     | 03    |
|                | Shelf Life, Ware House Operations<br>Management & Material Transactions | 03                    |                                 | 50                           | 50  |     |     |         | 100     | 03 |     | 03    |
|                | Industrial Electronics Product Design                                   | 03                    |                                 | 50                           | 50  |     |     |         | 100     | 03 |     | 03    |
|                | Pre-Production Activities   | 03                    |                                 | 50                           | 50  |     |     |         | 100     | 03 |     | 03    |
|                | Pre-Production Activities-Lab   |                       | 02                              |                              |     |     | 50  |         | 50      |    | 1.5 | 1.5   |
|                | Valuation & Storage-Lab   |                       | 02                              |                              |     |     | 50  |         | 50      |    | 1.5 | 1.5   |
|                | On Job Training   |                       | 18                              |                              |     | 100 |     |         | 100     |    | 15  | 15    |
|                | Total   | 12                    | 22                              | 200                          | 200 | 100 | 100 |         | 600     | 12 | 18  | 30    |
|                | Str   | ucture                | for Sem                         | ester-II                     |     |     |     |         |         |    |     |       |
| Course<br>Code | Course Name   | Tea<br>Sc<br>(Hou     | aching<br>heme<br>ırs/Wee<br>k) | Examination Scheme and Marks |     |     |     | Iarks   | Credits |    |     |       |
|                |   | Th                    | Prac                            | ISE                          | ESE | тw  | PR  | OR      | Total   | тн | PR  | Total |
|                | Entrepreneurship/   | 03                    |                                 | 50                           | 50  |     |     |         | 100     | 03 |     | 03    |
|                | Accounting/Management   | 03                    |                                 | 50                           | 50  |     |     |         | 100     |    |     | 03    |
|                | Project Work  |                       | 10                              |                              |     | 200 |     | 100     | 300     |    | 09  | 09    |
|                | On Job Training   |                       | 18                              |                              |     | 100 |     |         | 100     |    | 15  | 15    |
|                | Tota  | 06                    | 28                              | 100                          | 100 | 300 |     | 100     | 600     | 03 | 27  | 30    |

# B. Voc Electronics Manufacturing Services Syllabus for ThirdYear-

\*On Job Training should be carried out in any one subject per semester as per NSDC Guide lines for following Skill Sets:

- 1. Product Engineer (ELE/Q4201)
- 2. Incoming QC Technician (ELE/Q4401)
- 3. Assembly Supervisor (ELE/Q6305)
- 4. FPGA Design Engineer (ELE/Q8201)
- 5. Sales Executive-Consumer Electronics (ELE/Q3201)

### Third Year Syllabus

#### Name of the Course: B. Voc (Electronics Manufacturing Services)

#### Semester I

| Subject Name: Valuations & Storage |  |  |
|------------------------------------|--|--|
| Course Code :                      | Semester: I  |  |
| Weekly Teaching Hours: Theory : 03 | Scheme of Marking Theory: 100 Marks<br>Insem 30 Marks<br>Endsem 70 Marks |  |
| Credit : 3                         | Scheme of Marking PR:  |  |

|          | Content   | Hours |
|----------|---|-------|
| I Init 1 | MSD420 Microscontrollon Architecture and Low Dower Easture            | 10    |
| Unit I   | MSP450 Microcontroller Architecture and Low Power Feature             | 12    |
|          | Low Power 16-bit MSP430x5xx microcontroller architecture, address     |       |
|          | space, on-chip peripherals (analog and digital), and Register sets.   |       |
|          | Instruction set, instruction formats, and various addressing modes of |       |
|          | MSP430 devices; Variants of the MSP430 family viz. MSP430x2x,         |       |
|          | MSP430x4x, MSP430x5x and their targeted applications, System          |       |
|          | clocks. Low Power aspects of MSP430: low power modes                  |       |
| Unit 2   | Real World Interfacing  | 12    |
|          | GPIO programming and I/O multiplexing; Interrupts and interrupt       |       |
|          | programming. Watchdog timer. Timers & Real Time Clock (RTC),          |       |
|          | PWM control. Analog interfacing and data acquisition: ADC and         |       |
|          | Comparator in MSP430, data transfer using DMA. Serial                 |       |
|          | communication basics, Synchronous/Asynchronous interfaces (like       |       |
|          | UART. USB. SPI. and I2C). UART protocol. I2C protocol. SPI            |       |
|          | protocol. Implementing and programming UART, I2C, SPI interface       |       |
|          | using MSP430, Interfacing external devices                            |       |
| Unit 3   | ARM7  | 12    |
|          | Introduction to ARM processors and its versions. ARM7, ARM9 &         |       |
|          | ARM11 comparison, advantages & suitability in embedded application    |       |
|          | ARM7 data flow model, programmer"s model, modes of operations         |       |
| Unit 4   | ARM7 Based Microcontroller  | 09    |
|          | ARM7 Based Microcontroller LPC2148: Features, Architecture (Bloc      |       |
|          | Diagram and Its Description), System Control Block (PLL and VPI       |       |
|          | divider), Memory Map, GPIO, Pin Connect Block, timer, interfacin      |       |
|          | with LED, LCD, KEYPAD.  |       |

| Books           |                                |           |
|-----------------|--------------------------------|-----------|
| Name of Authors | Title of the Book              | Publisher |
| .Mazidi         | 8051 microcontroller & embedde |           |
|                 | system 3rd Edition             | Pearson   |
| Mazidi          | PIC microcontroller & embedded |           |
|                 | system 3rd Edition             | Pearson   |

| Subject Name: UPS and Inverter Technician |  |  |
|---|--|--|
| Course Code :                             | Semester: I  |  |
| Weekly Teaching Hours: Theory : 03        | Scheme of Marking Theory: 100 Marks<br>Insem 30 Marks<br>Endsem 70 Marks |  |
| Credit : 3                                | Scheme of Marking PR:  |  |

|  | Content   |  | Hours |
|--|---|--|-------|
| Unit 1   | Introduction  |  | 12    |
|  | Introduction to Inver   | er, Block diagram of Inverter, Rectifier, its type and |       |
|  | working principle,  |  |       |
| Unit 2   | Working of Invertor   |  | 12    |
|  | PIV of Diode, Filter  | employed in rectifier Battery charger circuit, working |       |
|  | of Inverter Oscillator  | , type of Oscillator, Square wave Generator PWM,       |       |
| Unit 3   | Designing Invertors   | Part 1   | 12    |
|  | DC to AC Convertor/Invertor, Designing an investor,                               |  |       |
| Unit 4   | Designing Invertors Part 1  |  | 09    |
|  | Circuit using PWM UPS, Working principle, specifications, explanation wit         |  |       |
| the help of block diagram, UPS Installation Find the total Load and Select |   |  |       |
|  | suitable Inverter/UPS   |  |       |
| Books  |   |  |       |
|  |   |  |       |
| Nai  | Name of Authors Title of the Book   |  |       |
| Abraham  | Abraham Pressman Switching Power Supply Design                                    |  |       |
| National   | National Instructional Media Repair & Maintenance of Power supply, Invertor & UPS |  | PS –  |
| Institute,   | Institute, Chennai NIMI   |  |       |

| Subject Name: Solar and LED Technician |  |  |
|--|--|--|
| Course Code :                          | Semester: I  |  |
| Weekly Teaching Hours: Theory : 03     | Scheme of Marking Theory: 100 Marks<br>Insem 30 Marks<br>Endsem 70 Marks |  |
| Credit : 3                             | Scheme of Marking PR:  |  |

|        | Content  | Hours |
|--------|--|-------|
| Unit 1 | Conditions, collect tools and raw materials                            | 12    |
|        | Understand the work requirement, Site condition, Understand the        |       |
|        | installation requirement ,Materials required for installation, Quality |       |
|        | material usage and appropriate handling mechanism                      |       |
| Unit 2 | Installation   | 12    |
|        | Installation and material usage procedure, Mounting requirements,      |       |
|        | Connection of the system and functioning, Report and document          |       |
|        | completion of work, Quality and safety procedures                      |       |
| Unit 3 | Coordination   | 12    |
|        | Company's policies on: Incentives, Delivery standards, and personnel   |       |
|        | management, Importance of the individual's role in the workflow,       |       |
|        | Reporting structure, How to communicate effectively, How to build      |       |
|        | team coordination  |       |
| Unit 4 | Safety and Precaution  | 09    |
|        | How to maintain the work area safe and secure, How to handle           |       |
|        | hazardous material, How to operate hazardous tools and equipment,      |       |
|        | Emergency procedures to be followed such as fire accidents, etc.       |       |

| Books            |  |           |
|------------------|--|-----------|
| Name of Authors  | Title of the Book  | Publisher |
| Adrian Kitai     | Principles of Solar Cells, LEDs and Diodes                             | Wiley     |
| Gregory F. Nemet | How Solar Energy Became Cheap:<br>A Model for Low-Carbon<br>Innovation | Routledge |

| Subject Name: Industrial Electronic Product Design |  |  |
|--|--|--|
| Course Code : Semester: I                          |  |  |
| Weekly Teaching Hours: Theory : 03                 | Scheme of Marking Theory: 100 Marks<br>Insem 30 Marks<br>Endsem 70 Marks |  |
| Credit : 3   | Scheme of Marking PR:  |  |

| Contents |   | Hours |
|----------|---|-------|
|          |   |       |
| Unit 1   | Introduction, Development Process, Product Planning &               | 12    |
|          | Conceptualization   |       |
| Unit 2   |   | 12    |
|          | Product Architecture and Industrial Design                          |       |
| Unit 3   | Product Manufacturing & Prototyping                                 | 12    |
|          |   |       |
| Unit 4   | Economic Analysis & Managing projects, Introduction to 3-D printing | 09    |
|          | and Rapid Prototyping   |       |

| Books           |  |                       |
|-----------------|--|-----------------------|
| Name of Authors | Title of the Book                                      | Publisher             |
| Bert Haskell    | Portable Electronics Product<br>Design and Development | McGraw-Hill Companies |
| Tony Serksnis   | Designing Electronic Product<br>Enclosures             | Springer              |

| Subject Name: Embedded System – Lab |   |  |
|-------------------------------------|---|--|
| Course Code : Semester: I           |   |  |
| Weekly Practicals: PR: 01           | Scheme of Marking TH:                       |  |
| TH Exam Duration:                   | Scheme of Marking PR: 25, IA: 25, Total: 50 |  |
| Credit:1.5                          |   |  |

| Sr. No. | Laboraty   |
|---------|--|
| 1       | Interfacing LPC2148 to LCD   |
| 2       | UART Interfacing LPC2148 in embedded system (GSM/GPS)                  |
| 3       | Interfacing SD card to LPC2148   |
| 4       | Interfacing EEPROM to LPC2148 using I2C protocol                       |
| 5       | Interfacing LPC2148 to Seven Segment / RGB LED                         |
| 6       | Generation of PWM signal for motor control using LPC2148               |
| 7       | Interfacing TFT display to LPC2148 17. Implementing CAN protocol using |
|         | LPC214   |

| Subject Name: Pre-Production, Valuations and Storage – Lab |   |  |  |  |
|--|---|--|--|--|
| Course Code :  | Semester: I                                 |  |  |  |
| Weekly Practicals: PR: 01                                  | Scheme of Marking TH:                       |  |  |  |
| TH Exam Duration:  | Scheme of Marking PR: 25, IA: 25, Total: 50 |  |  |  |
| Credit:1.5   |   |  |  |  |

| Sr. No. | Laboraty   |
|---------|--|
| 1       | Production activities - Two Hand Insertion                             |
| 2       | Production activities - Positioning of Bins                            |
| 3       | House Keeping - 5S   |
| 4       | Categorization of Raw Material & Consumables - Hazardous/Non-Hazardous |
| 5       | Categorization of Raw Material & Consumables - Imported/Local          |
| 6       | Categorization of Raw Material & Consumables - Assembly/Parts          |
| 7       | Categorization of Raw Material & Consumables - Class A/B/C             |
| 8       | Categorization of Raw Material & Consumables - Good/defective          |

#### Third Year Syllabus

#### Name of the Course: B. Voc (Electronics Manufacturing Services)

#### Semester II

| Subject Name: Entrepreneurship/Accounting/Management |  |  |  |  |
|--|--|--|--|--|
| Course Code :  | Semester: II   |  |  |  |
| Weekly Teaching Hours: Theory : 03                   | Scheme of Marking Theory: 100 Marks<br>Insem 30 Marks<br>Endsem 70 Marks |  |  |  |
| Credit : 3   | Scheme of Marking PR:  |  |  |  |

| Contents |  | Hours |
|----------|--|-------|
| Unit 1   | Introduction   | 09    |
|          | Meaning and Nature of Management, Management Approaches,             |       |
|          | Processes, Managerial Skills, Tasks and Responsibilities of a        |       |
|          | Professional Manager   |       |
| Unit 2   | Organizational Structure and Process                                 | 09    |
|          | Organizational Culture and Climate, Managerial Ethos, Organization   |       |
|          | Structure & Design, and Managerial Communication                     |       |
| Unit 3   | Planning and Controlling   | 09    |
|          | Planning Types and Process, Management by Objectives, Decision-      |       |
|          | Making Types and Models, Problem Solving Techniques, Controlling     |       |
|          | Process and Techniques   |       |
| Unit 4   | Performance Evaluation Techniques                                    | 09    |
|          | Introduction to Budgeting and Budgetary Control; Performance         |       |
|          | Budgeting; Classification of Budget; Standard Costing and Variance   |       |
|          | Analysis; Balanced Scorecard; Responsibility Accounting              |       |
| Unit 5   | Decision Making Techniques   | 09    |
|          | Cost Volume Profit Analysis; Management Accounting for Decision      |       |
|          | Making and Control; EVA and Performance Measurement;                 |       |
|          | Introduction to Activity Base Costing, Targeting Costing, Life Cycle |       |
|          | Costing; Uniform Costing   |       |

| Books  |  |                    |  |  |
|--|--|--------------------|--|--|
| Name of Authors                                    | Title of the Book  | Publisher          |  |  |
| Michael Kraten                                     | Business Planning and<br>Entrepreneurship: An<br>Accounting Approach | Business Expert    |  |  |
| Ratih Hurriyati, Benny<br>Tjahjono, Ikuro Yamamoto | Advances in Business,<br>Management and<br>Entrepreneurship          | CRC Press/ Bulkema |  |  |